



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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企业微信二维码



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Features

- $BV_{CEO} > 150V$
- $I_C = 5A$ High Continuous Collector Current
- $I_{CM} = 10A$ Peak Pulse Current
- Very Low Saturation Voltage $V_{CE(sat)} < 110mV @ 1A$
- $R_{CE(sat)} = 50m\Omega$ for a Low Equivalent On-Resistance
- h_{FE} Specified Up to 10A for a High Gain Hold-Up
- Complementary PNP Type: NK-FZT955

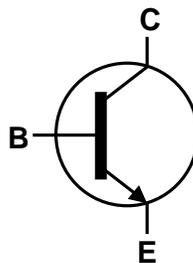
Mechanical Data

- Package: SOT223 (Type DN)
- Package Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 
- Weight: 0.112 grams (Approximate)

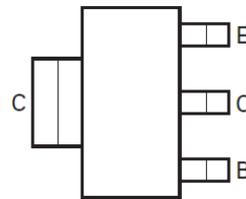
SOT223 (Type DN)



Top View



Device Symbol



Top View
Pin-Out

Absolute Maximum Ratings (@ $T_A = +25^{\circ}\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CB0}	250	V
Collector-Emitter Voltage	V_{CEO}	150	V
Emitter-Base Voltage	V_{EBO}	7	V
Continuous Collector Current	I_C	5	A
Peak Pulse Current	I_{CM}	10	A
Base Current	I_B	1	A

Thermal Characteristics (@ $T_A = +25^{\circ}\text{C}$, unless otherwise specified.)

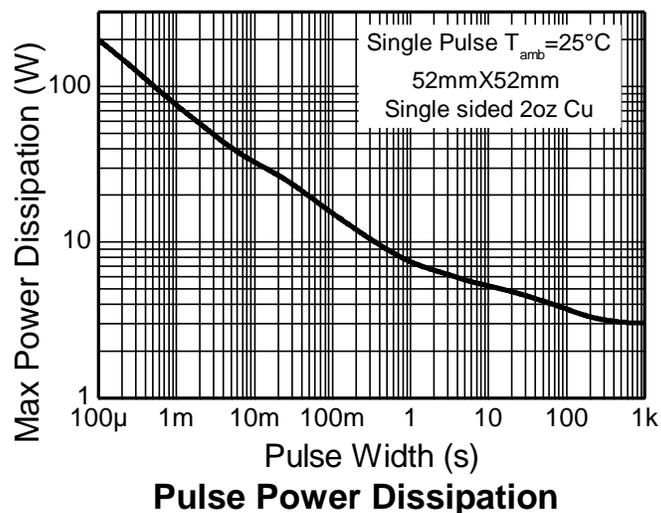
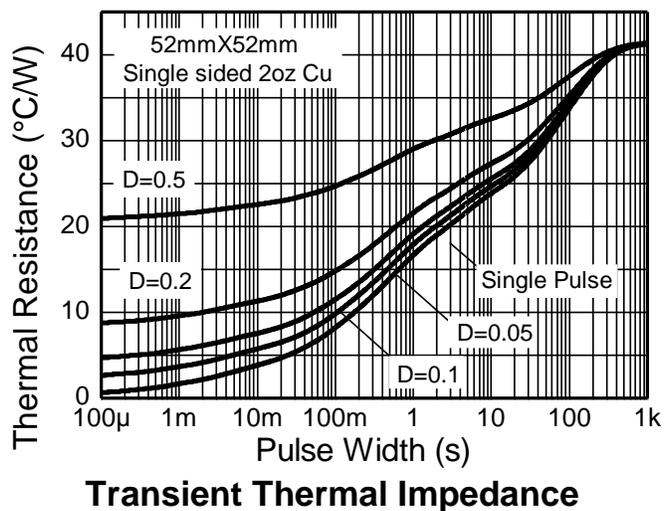
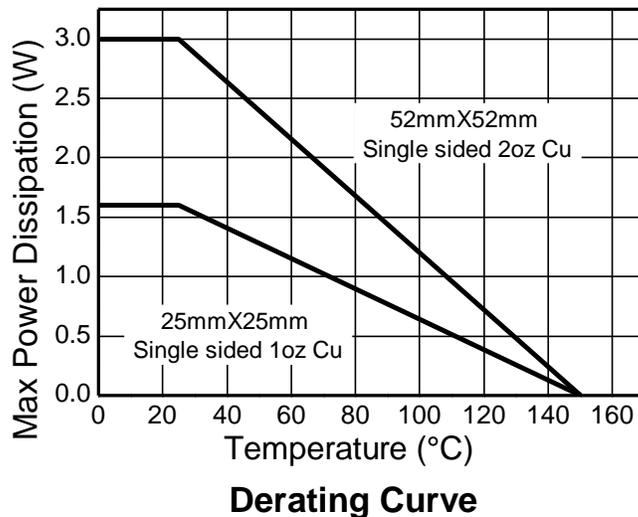
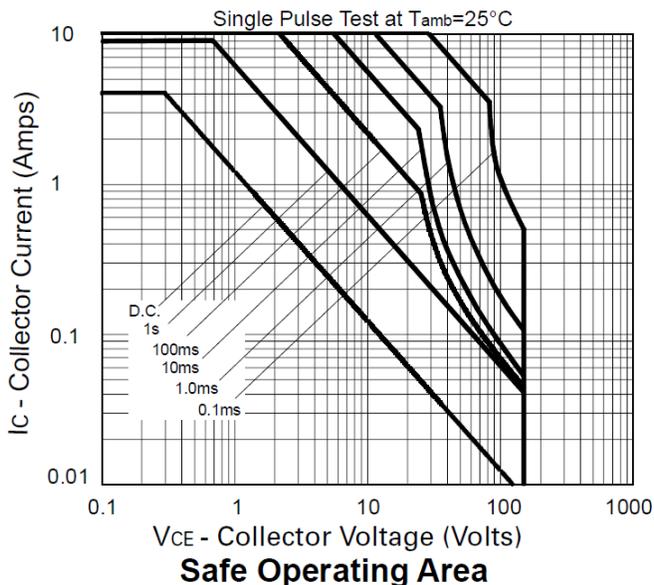
Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor	P_D	3.0	W
		24	
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	1.6	$\text{mW}/^{\circ}\text{C}$
		12.8	
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	42	$^{\circ}\text{C}/\text{W}$
		78	
Thermal Resistance Junction to Lead	$R_{\theta JL}$	8.8	$^{\circ}\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^{\circ}\text{C}$

ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	$\geq 8,000$	V	3B
Electrostatic Discharge - Machine Model	ESD MM	≥ 400	V	C

- Notes:
5. For a device surface mounted on 52mm X 52mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; device measured when operating in steady state condition.
 6. Same as Note 5, except the device is mounted on 25mm x 25mm single sided 1oz weight copper.
 7. Thermal resistance from junction to solder-point (at the end of the collector lead).
 8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

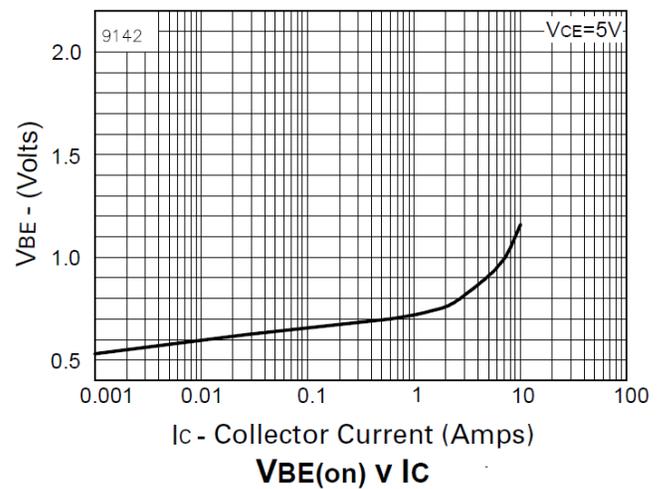
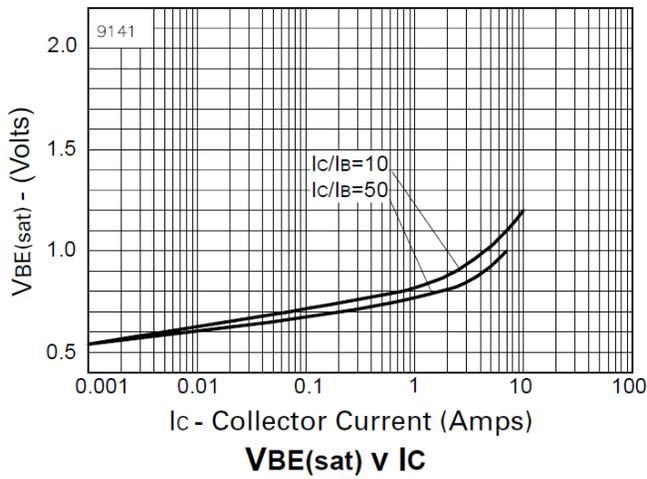
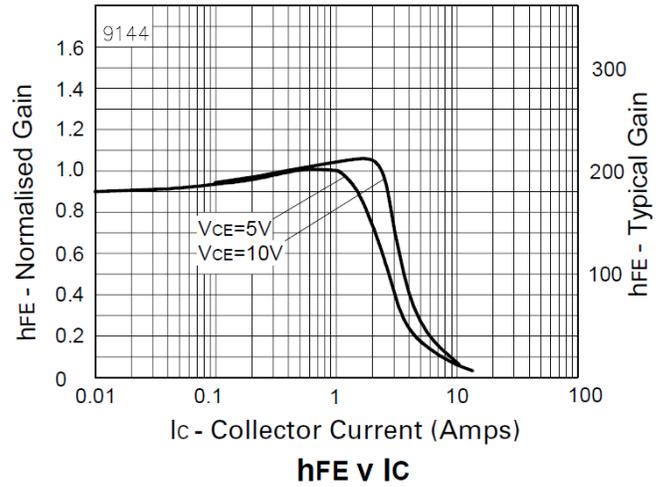
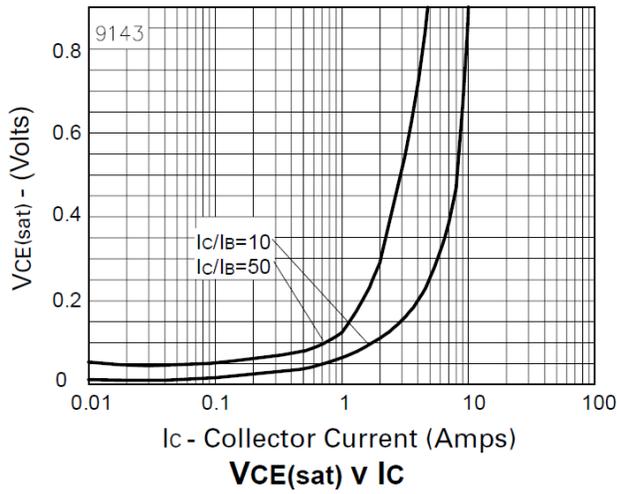


Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	250	375	—	V	$I_C = 100\mu\text{A}$
Collector-Emitter Breakdown Voltage	BV_{CER}	250	375	—	V	$I_C = 1\mu\text{A}, R_B \leq 1\text{k}\Omega$
Collector-Emitter Breakdown Voltage (Note 9)	BV_{CEO}	150	180	—	V	$I_C = 1\text{mA}$
Emitter-Base Breakdown Voltage	BV_{EBO}	7	8	—	V	$I_E = 100\mu\text{A}$
Collector Cut-Off Current	I_{CBO}	—	—	50 1	nA μA	$V_{CB} = 200\text{V}$ $V_{CB} = 200\text{V}, @T_A = +100^\circ\text{C}$
Collector Cut-Off Current	I_{CER}	—	—	50 1	nA μA	$V_{CE} = 200\text{V}, R \leq 1\text{k}\Omega$ $V_{CE} = 200\text{V}, @T_A = +100^\circ\text{C}$
Emitter Cut-Off Current	I_{EBO}	—	—	10	nA	$V_{EB} = 6\text{V}$
Collector-Emitter Saturation Voltage (Note 9)	$V_{CE(sat)}$	—	20 35 60 260	40 65 110 355	mV	$I_C = 100\text{mA}, I_B = 5\text{mA}$ $I_C = 500\text{mA}, I_B = 50\text{mA}$ $I_C = 1\text{A}, I_B = 100\text{mA}$ $I_C = 5\text{A}, I_B = 500\text{mA}$
Base-Emitter Saturation Voltage (Note 9)	$V_{BE(sat)}$	—	—	1,250	mV	$I_C = 5\text{A}, I_B = 500\text{mA}$
Base-Emitter Turn-On Voltage (Note 9)	$V_{BE(on)}$	—	—	1,100	mV	$I_C = 5\text{A}, V_{CE} = 5\text{V}$
DC Current Gain (Note 9)	h_{FE}	100 100 15 —	200 200 30 10	— 300 — —		$I_C = 10\text{mA}, V_{CE} = 5\text{V}$ $I_C = 1\text{A}, V_{CE} = 5\text{V}$ $I_C = 5\text{A}, V_{CE} = 5\text{V}$ $I_C = 10\text{A}, V_{CE} = 5\text{V}$
Current Gain-Bandwidth Product (Note 9)	f_T	—	90	—	MHz	$V_{CE} = 10\text{V}, I_C = 100\text{mA}$ $f = 50\text{MHz}$
Output Capacitance	C_{obo}	—	22	—	pF	$V_{CB} = 10\text{V}, f = 1\text{MHz}$
Switching Times	t_{on} t_{off}	—	66 2,130	—	ns ns	$I_C = 1\text{A}, V_{CC} = 50\text{V}$ $I_{B1} = -I_{B2} = 100\text{mA}$

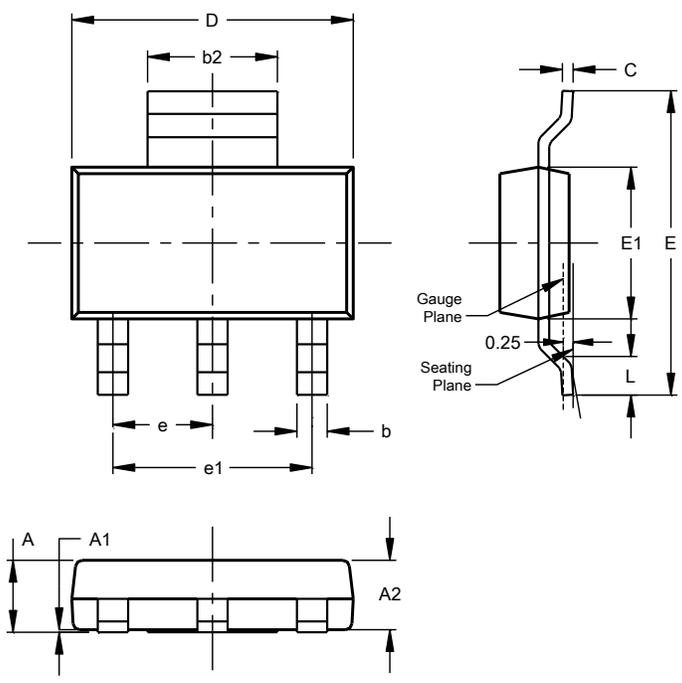
Note: 9. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

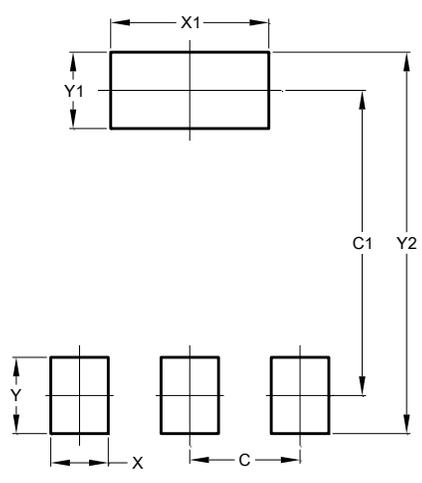
SOT223 (Type DN)



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Dim	Min	Max	Typ
A	--	1.70	--
A1	0.01	0.15	--
A2	1.50	1.68	1.60
b	0.60	0.80	0.70
b2	2.90	3.10	--
c	0.20	0.32	--
D	6.30	6.70	--
E	6.70	7.30	--
E1	3.30	3.70	--
e	--	--	2.30
e1	--	--	4.60
L	0.85	--	--
All Dimensions in mm			

Suggested Pad Layout

SOT223 (Type DN)



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00